

**TECHNICAL SPECIFICATION**

HOUSING MATERIAL : THERMOPLASTIC POLYESTER UL94V0; GREY  
 HOUSING CAN WITHSTAND EXPOSURE TO LEAD FREE WAVE SOLDERING TEMPERATURE OF 260-265°C  
 WHEN USED WITH PROTECTIVE ADHESIVE OR PROTECTIVE METALLIC DEVICE FOR ANGLE CONNECTORS AS  
 IT IS USED IN CLASSICAL LEAD WAVE SOLDERING AT 235-250°C.  
 CONTACT & HARPOON MATERIAL : COPPER ALLOY  
 CONTACT PLATING :  
 CONTACT ZONE : Au OVER Ni  
 TERMINATION ZONE : Sn (PURE MATT) OVER Ni FOR LEAD FREE VERSION  
 HARPOON PLATING : Sn (PURE MATT) OVER Ni FOR LEAD FREE VERSION

**ELECTRICAL DATA**

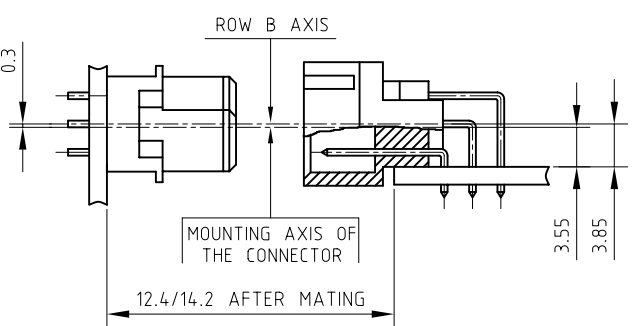
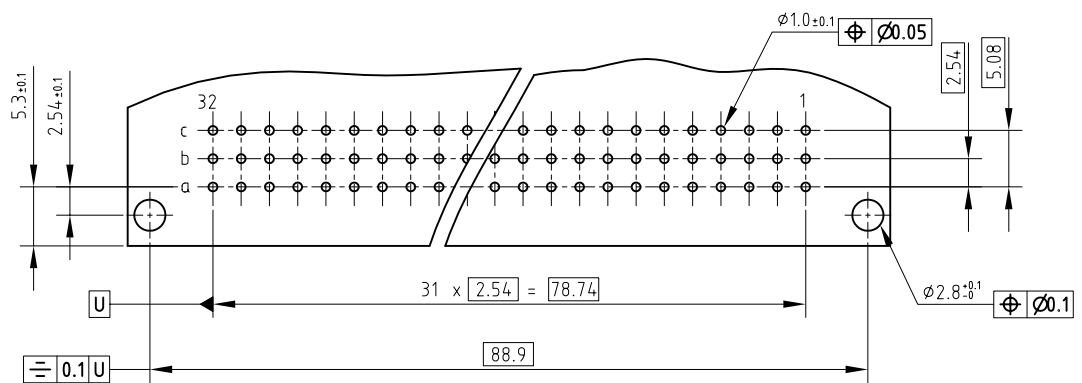
CURRENT RATING AT 20°C : 1.5 A  
 CURRENT (I MAX) : 2 A  
 TEMPERATURE RANGE : -55°C TO +125°C  
 CONTACT RESISTANCE : ≤ 20mΩ  
 INSULATION RESISTANCE : ≥ 10<sup>6</sup> MΩ  
 TEST VOLTAGE (rms) : 1000 V

**MECHANICAL DATA**

INSERTION FORCE PER CONTACT : ≤ 0.94 N  
 EXTRACTION FORCE PER CONTACT : ≥ 0.15 N

REFERENCE SPECIFICATION : DIN 41612 / IEC 603-2

**PCB DRILLING DETAILS**



SERIES	8609	3	64	7	1	13	H	8	0	SKLF
ROWS FITTED WITH CONTACTS										
ROW a b c	3 64									
NO. OF CONTACTS										
TYPE OF INSULATOR	3 ROW MALE INSULATOR									
METHOD OF MOUNTING	STANDARD MOUNTING - STYLE C									
TERMINATION	ANGLED SPILL									
OPTIONS	NO OPTION									
	WITH HARPOONS									
PERFORMANCE CLASS										
DIN 41612 CLASS 3	4									
DIN 41612 CLASS 2	5									
DIN 41612 CLASS 1	6									
AS PER MIL C 55302 / JSS 50808	8									
PITCH PER ROW	MIXED PITCH									
SPECIAL CODE: SPECIAL LOADING OF CONTACTS, LEAD FREE VERSION	SKLF									
CONTACTS LOADED ONLY IN	a: 1,2,3,4,5,6,7,8,9,10,11,12,13,14,15,16,17,18,19,20,21,22,23,24,25,26,27,28,29,30,31,32									
	b: 2,4,6,8,10,12,14,16,18,20,22,24,26,28,30,32									
	c: 2,4,6,8,10,12,14,16,18,20,22,24,26,28,30,32									

**NOTES:**

- THE "LF" PRODUCTS MEET EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 3.5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6 MM MINIMUM THICK CIRCUIT BOARD.
- LEAD FREE OR RoHS DIRECTIVE LABELING TO BE PROVIDED AS PER GS-14-920 FOR LEAD FREE VERSION.

mat'l. code	surface	tolerance	projection	product family
SEE TECH. SPEC.	ISO 1302 ✓	ISO 406 ISO 1101		8609
ltr	ecn no	dr	date	title
A	110-0164	SAL	2010-08-16	DIN STANDARD HEADER ANGLED SPILL DIN 41612 STYLE-C
				angles
				linear
				0°±1°
				dr
				engr
				chr
				appd
sheet	revision	A		scale 3:2
index	sheet	1		
				dwg no
				sheet 1 of 1
				size
				A3
				type
				Product Customer Drawing



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